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FEB 10 2005

**PATENT
YOR19960184N IBM-219**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	D.Y.Shih, et al.
Serial Number	:	09/254,769
Filing Date	:	March 11, 1999
Examiner	:	V. Nguyen
Group Art Unit	:	2829
For	:	WAFER SCALE HIGH DENSITY PROBE ASSEMBLY, APPARATUS FOR USE THEREOF AND METHODS OF FABRICATION THEREOF

Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated February 7, 2005, please amend the above-identified application as follows:

IN THE CLAIMS:

Cancel Claims 34-45, 50-51.

REMARKS

The Examiner is requested to reconsider his rejection of Claims 8 and 32. In the Official Action dated April 8, 2004, the Examiner rejected Claims 8 and 32 under 35 USC 112, second

-1-

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